

1025HC

Fast-acting, high current, surface mount ceramic tube fuses



Product description

- · Fast-acting high current fuse
- · Compact design utilizes less board space
- 20 A to 50 A current ratings
- Ceramic tube, silver plated brass end cap construction
- Halogen free and RoHS compliant

Applications

Primary and secondary circuit protection:

- Server and desktop power supplies
- · Gaming console systems
- Voltage Regulator Module (VRM)
- · Storage system power
- · Base station power supplies
- · Basic power supplies
- · LED and general lighting
- · Test equipment

Agency information

- cURus Recognition file number: E19180, Guide JDYX2/JDYX8
- PSE: JET 7042-31007-1002 (20 A to 30 A)

Ordering

• Use ordering number (see page 7 for details)

Packaging suffixes

 -TR (20 A to 30 A: 1500 parts per 13" diameter reel, tape width 24 mm) (40 A to 50 A: 1000 parts per 13" diameter reel, tape width 24 mm)



Electrical characteristics

% of Amp Rating	Opening Time
100	4 hours minimum
200	60 s maximum

Product specifications

Part number ⁴	Current rating (A)	Voltage rating (V _{AC})	Voltage rating (V _{DC})	Interrupting rating at rated voltage (A _{AC})	Interrupting rating at rated voltage ¹ (A _{DC})	Typical DC cold resistance 2 ($m\Omega$)	Typical melting³ I²t (A²s)	Part marking	cURus	PSE
1025HC20-R	20	250	72	100	500	3.1	25	<ps> E JET BUSS 20A</ps>	Х	Х
1025HC25-R	25	250	72	100	500	2.6	50	<ps> E JET BUSS 25A</ps>	Х	Х
1025HC30-R	30	250	72	100	500	1.7	112	<ps> E JET BUSS 30A</ps>	Х	Х
1025HC40-R	40	250	72	100	500	1.3	400	BUSS 40A	Х	
1025HC50-R	50	NA	60	NA	600	1.1	600	BUSS 50A	Х	

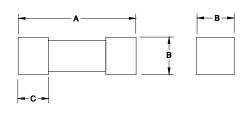
¹ DC interrupting rating measured at rated voltage, time constant of less than 1.0 microseconds, battery source

1025HC= Product code and size

xx= Ampere rating

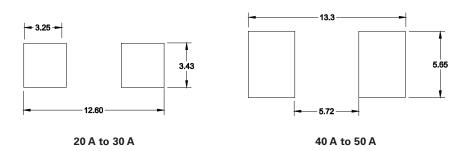
-R= Rohs compliant

Dimensions (mm)



Rating	Α	В	С
20 A to 30 A	10.0 ±0.50	3.15 ±0.15	1.70 ±0.15
40 A to 50 A	12.4 ±0.50	4.50 ±0.15	2.70 ±0.15

Recommended pad layout (mm)



Recommended trace thickness is 3 oz.

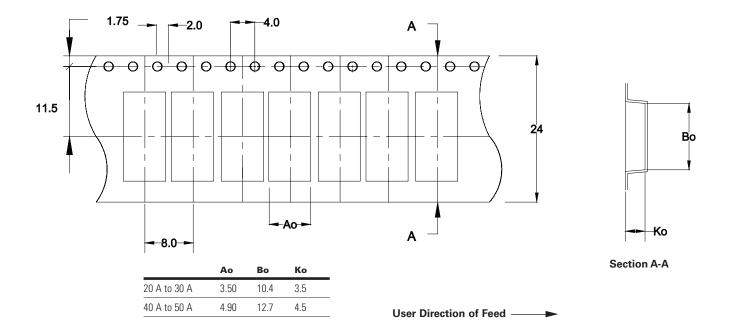
Recommended min-trace width is 10 mm (20 A to 30 A) and 15 mm (40 A to 50 A)

² Typical DC cold resistance measured at <10% of rated current at an ambient temperature of 20 °C (reference only)

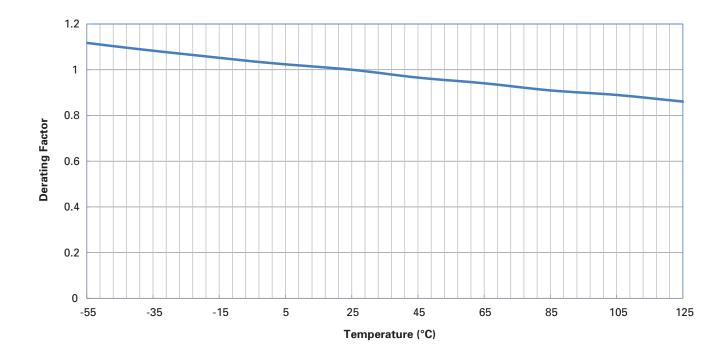
^{3.} Typical melting I2t value is measured at 10ln rated current

^{4.} Part number definition: 1025HCxx-R

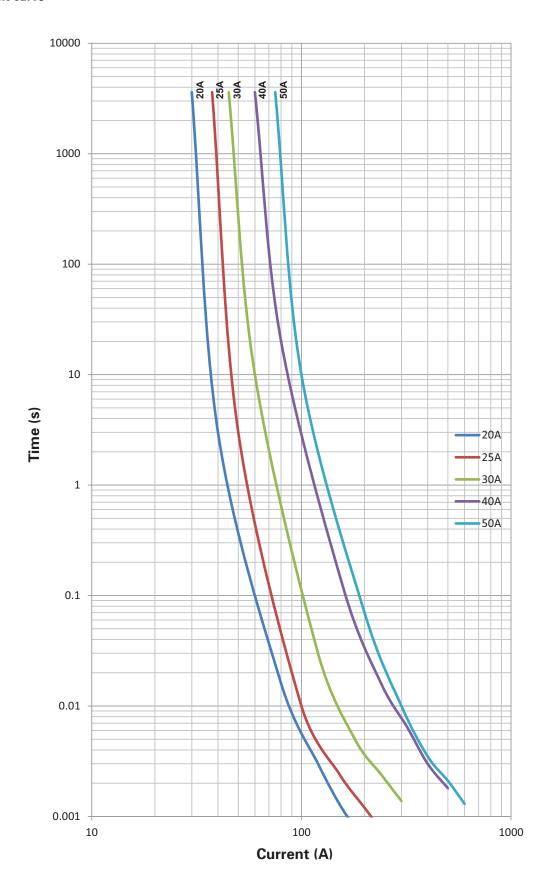
Packaging information (mm)



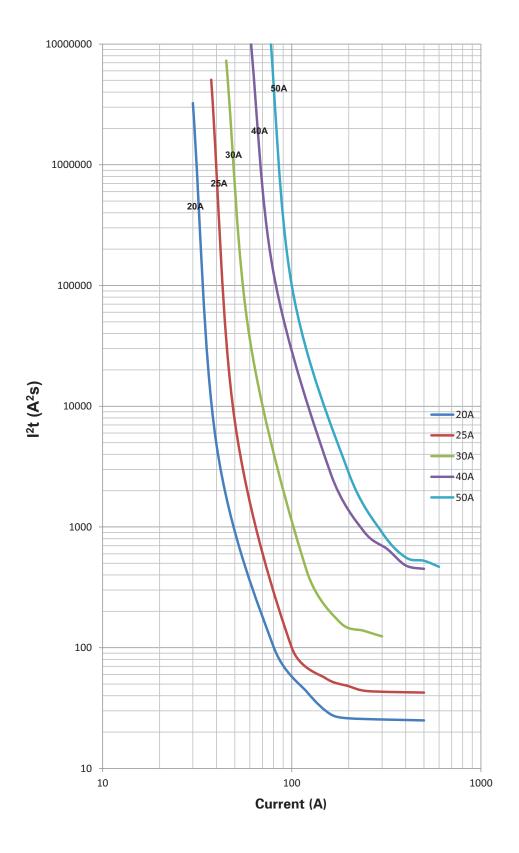
Temperature derating curve



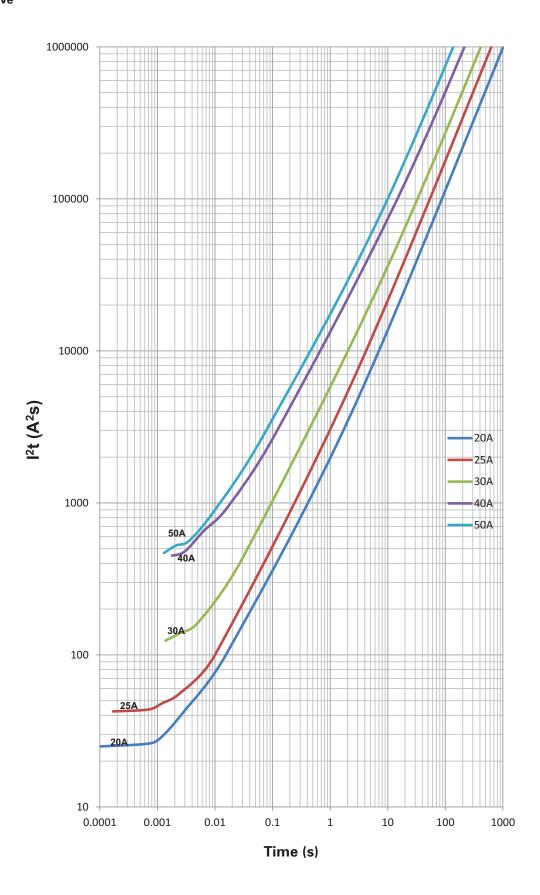
Time vs. current curve



l²t vs. current curve



I²t vs. time curve



Environmental data

Operating temperature: - 55 °C to 125 °C (with derating)
Thermal cycling: (100 cycles - 55 °C to 125 °C)
Vibration: (20 g's, 10 Hz - 2000 Hz)
Board flex: 60 s, 2 mm
Mechanical shock: 3000 g, 0.3 ms
Termination strength: 1.8 kg, 60 s
Solderability test: J-STD- 002, Method B1, G1 and D

Ordering codes

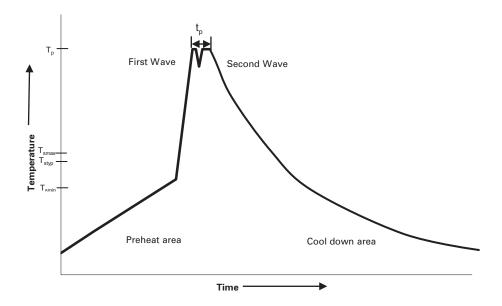
The ordering code is the part number adding the packaging suffix.

	Ordering codes	
Part number	-TR option	
1025HC20-R	1025HC20-RTR	
1025HC25-R	1025HC25-RTR	
1025HC30-R	1025HC30-RTR	
1025HC40-R	1025HC40-RTR	
1025HC50-R	1025HC50-RTR	

Packaging suffixes

• -TR (20 A to 30 A: 1500 parts per 13" diameter reel, tape width 24 mm) (40 A to 50 A: 1000 parts per 13" diameter reel, tape width 24 mm)

Wave solder profile

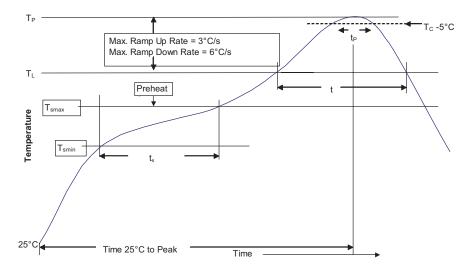


Reference EN 61760-1:2006

Profile Feat	ure	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat	• Temperature min. (T _{smin})	100 °C	100 °C
	• Temperature typ. (T _{Styp})	120 °C	120 °C
	• Temperature max. (T _{smax})	130 °C	130 °C
	• Time (T _{smin} to T _{smax}) (t _s)	70 seconds	70 seconds
Δ preheat to r	max Temperature	150 °C max.	150 °C max.
Peak temperat	ture (Tp)*	235 °C − 260 °C	250 °C − 260 °C
Time at peak t	emperature (t _p)	10 seconds max 5 seconds max each wave	10 seconds max 5 seconds max each wave
Ramp-down ra	ate	~ 2 K/s min ~3.5 K/s typ ~5 K/s max	~ 2 K/s min ~3.5 K/s typ ~5 K/s max
Time 25 °C to	25 °C	4 minutes	4 minutes

Manual solder 350 °C, 4-5 seconds (by soldering iron), generally manual, hand soldering is not recommended.

Solder reflow profile



-_{Tc-5°C} Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5mm)	235 °C	220 °C
≥2.5mm	220 °C	220 °C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6mm	260 °C	260 °C	260 °C
1.6 – 2.5mm	260 °C	250 °C	245 °C
>2.5mm	250 °C	245 °C	245 °C

Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak • Temperature min. (T _{smin})	100 °C	150 °C
• Temperature max. (T _{smax})	150 °C	200 °C
• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_{p}	3 °C/ Second Max.	3 °C/ Second Max.
Liquidous temperature (TL) Time at liquidous (tL)	183 °C 60-150 Seconds	217 °C 60-150 Seconds
Peak package body temperature (Tp)*	Table 1	Table 2
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})	6 °C/ Second Max.	6 °C/ Second Max.
Time 25 °C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

^{*} Tolerance for peak profile temperature (T_n) is defined as a supplier minimum and a user maximum.

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^{**} Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum.